

Title (en)

IMPROVED LEADFRAME STRUCTURE WITH PREPLATED LEADS AND PROCESS FOR MANUFACTURING THE SAME

Title (de)

VERBESSERTE LEITERRAHMERSTRUKTUR MIT VORPLATIERTEN FINGERN UND HERSTELLUNGSVERFAHREN DAFÜR

Title (fr)

STRUCTURE DE GRILLE DE CONNEXION AMELIOREE A CONNECTEURS PREMÉTALLISÉS ET PROCÉDE DE FABRICATION

Publication

**EP 1021831 A1 20000726 (EN)**

Application

**EP 98910140 A 19980105**

Priority

- US 9804119 W 19980105
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Abstract (en)

[origin: WO9834277A1] An improved leadframe structure, process of manufacturing the same, and improved IC package (190) and packaging process using the same are provided. The leadframe includes a plurality of leads (85) having inner portions (95) located within an IC encapsulation area and outer portions (80) extending outside the encapsulation area into contact with the outside environment. A plating mask cooperates with a polymer structure having a preselected configuration to form a substantially fluid-tight gasket to facilitate selective preplating (92) of the outer portions of the leads of the leadframe prior to beginning the IC packaging process. Since the polymer structure (160) is electrically insulative, concerns regarding plating mask (200) misalignment are minimized.

IPC 1-7

**H01L 23/48**

IPC 8 full level

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Citation (search report)

See references of WO 9834277A1

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